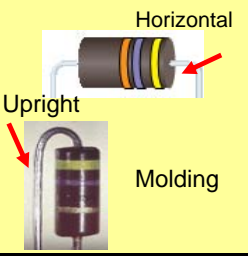
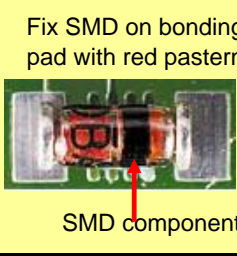
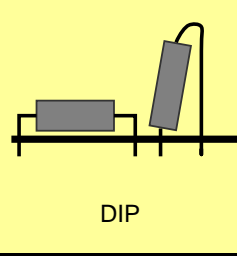
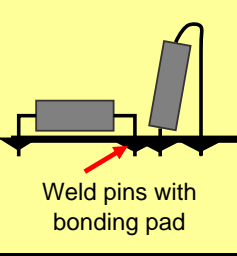
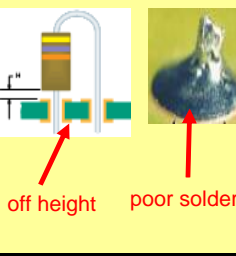

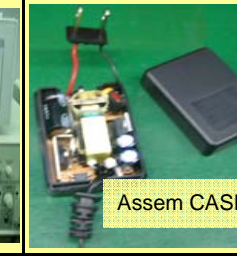
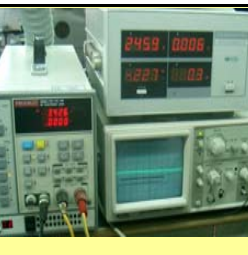
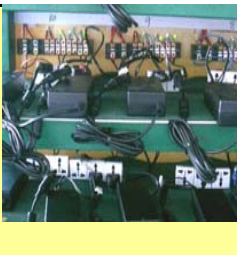







# SHENZHEN GUCF TECHNOLOGY CO.,LTD

## Power adapter process flow diagram

|            |   |   |   |  |   |   |   |
|------------|---|---|---|--|---|---|---|
| Facilities | Process   | SMT   | DIP   | Solder   | Repair  | Test 1  | Assem   |
|            | Forming,PCB cutter  | SMT machine   | DIP Line  | Lead-free Wave Solder  | Sear-iron,jig and fixture   | Load analyzer,ondoscope   | ultrasonic wave apparatus   |
| Function   | ◆Process the component into suitable form   | ◆Stick SMD on PCB   | ◆Insert the DIP on PCB  | ◆Weld  | ◆Repair tilt and off height<br>◆repair poor solder                                  | ◆Test   | ◆Weld AC pin/inlet,DC cord<br>◆Assem CASE   |
| Diagram    |  |  |  |  |  |  |  |
| QC point   | 1.Process method<br>2.Processing size   | 1.SMT place<br>2.Component polarity   | 1.DIP place<br>2.component polarity   | 1.Welding quality<br>2.Temp.,speed,angle of tin stove                              | 1.Whether parts tilt and off height<br>2.Whether poor solder                        | 1.Output voltage&current waveform and protection test                               | 1.view appearance<br>2.assemble action  |

|            |   |   |   |  |   |   |   |          |
|------------|---|---|---|--|---|---|---|----------|
| Facilities | Test2   | Aging   | HI-POT  | Test   | Stick label   | Packing   | OQC   | Shipment |
|            | Load analyzer,ondoscope   | Booster,Aging rack  | Over Voltage&Insulation Tester  | Automatic tester   |   |   |   |          |
| Function   | ◆Semiproduct test   | ◆Aging the products on aging rack 2-4H  | ◆HI-POT insulation test   | ◆Automatic tester  | ◆Eye survey after sticking label  | ◆Packing as customer confirmed  | ◆OQC final verify   |          |
| Diagram    |  |  |  |  |  |  |  |          |
| QC point   | 1.Output voltage&current waveform and protection test                               | 1.Input&output voltage<br>2.Aging resistance value                                  | 1.Hi-pot test<br>2.Insulation resistance test                                       | 1.Overall test   | 1.Appearance  | 1.Package according to Approval Sheet   | 1.Electrical test,Drop test<br>Appearance inspection<br>Quantity confirm              |          |